

AMENDMENTS TO THE CLAIMS:

Claims 1-10 (cancelled)

11. (Currently Amended) A method for assembling an integral electronic device, comprising:

~~in an opening that extends completely through a thickness of a first board, holding an electronic component; and~~

holding a plurality of LEDs in openings that extend completely through a thickness of a first board, with each of said openings

(i) being defined by a side wall that is capable of shielding light emitted from a corresponding one of said plurality of LEDs,

(ii) being defined so as to limit movement of said corresponding one of said plurality of LEDs within the opening, and

(iii) having an arrangement accuracy corresponding to an arrangement accuracy required of said corresponding one of said plurality of said LEDs; and

electrically connecting a second board to said ~~electronic component~~ plurality of LEDs, thereby providing an integral electronic device including said first board, said ~~electronic component~~ plurality of LEDs and said second board.

12. (Currently amended) The method according to claim 11, wherein electrically connecting a second board to said ~~electronic component~~ plurality of LEDs comprises electrically connecting said second board to said ~~electronic component~~ plurality of LEDs via a flat metallic ~~bump~~ bumps.

13. (Currently amended) The method according to claim 12, wherein electrically connecting said second board to said ~~electronic component~~ plurality of LEDs via a flat metallic ~~bump~~ bumps comprises flattening a metallic ~~bump~~ bumps that is are on said second board and then connecting said metallic ~~bump~~ bumps to said ~~electronic component~~ plurality of LEDs.

Claim 14 (cancelled)

15. (Currently amended) The method according to claim ~~14~~ 11, wherein
holding ~~a light-emitting element~~ said plurality of LEDs in said ~~opening~~ openings comprises
holding said ~~light-emitting element~~ plurality of LEDs in ~~an opening~~ openings of a board of any one
of glass, ceramic and an organic resin.

16. (Currently amended) The method according to claim ~~15~~ 11, wherein
holding said ~~light-emitting element~~ said plurality of LEDs in said ~~opening~~ openings
comprises holding said ~~light-emitting element~~ plurality of LEDs in said ~~opening~~ openings via a
photo-curing insulating resin.

17. (Currently amended) The method according to claim ~~14~~ 13, wherein
holding said ~~light-emitting element~~ plurality of LEDs in said ~~opening~~ openings comprises
holding said ~~light-emitting element~~ plurality of LEDs in said ~~opening~~ openings via a photo-curing
insulating resin.

Claim 18 (cancelled)

19. (Currently amended) The method according to claim ~~18~~ 15, wherein
holding said ~~electronic component~~ plurality of LEDs in said ~~opening~~ openings comprises
holding said ~~electronic component~~ plurality of LEDs in said ~~opening~~ openings via a photo-curing
insulating resin.

20. (Currently amended) The method according to claim ~~11~~ 37, wherein
holding said ~~electronic component~~ plurality of LEDs in said ~~opening~~ openings comprises
holding said ~~electronic component~~ plurality of LEDs in said ~~opening~~ openings via a photo-curing
insulating resin.

21. (Currently amended) The method according to claim 11, wherein holding said ~~electronic component~~ plurality of LEDs in said opening openings comprises holding said ~~electronic component~~ plurality of LEDs in said opening openings via an insulating resin that surrounds each of said ~~electronic component~~ plurality of LEDs except for upper and lower surfaces of said ~~electronic component~~ each of said plurality of LEDs.

22. (Currently amended) The method according to claim 21, wherein electrically connecting a second board to said ~~electronic component~~ plurality of LEDs comprises electrically connecting said second board to said upper ~~surface~~ surfaces of said ~~electronic component~~ each of said plurality of LEDs, said method further comprising:

electrically connecting a third board to said lower ~~surface~~ surfaces of said ~~electronic component~~ each of said plurality of LEDs.

23. (Currently amended) The method according to claim 11, further comprising: in another opening that extends completely through the thickness of said first board, holding another ~~electronic component~~ LED; and

electrically connecting said second board to said another ~~electronic component~~ LED while said another ~~electronic component~~ LED is held in said another opening,

wherein said opening openings and said another opening are parallel to one another.

24. (Withdrawn) An integral electronic device comprising: a first board having an opening that extends completely through a thickness of said first board;

an electronic component held within said opening; and

a second board electrically connected to said electronic component.

25. (Withdrawn) The integral electronic device according to claim 24, wherein

said electronic component comprises a light-emitting element and said opening is defined by a side wall that is capable of shielding light emitted from said light-emitting element.

26. (Withdrawn) The integral electronic device according to claim 25, wherein said first board comprises a board of any one of glass, ceramic and an organic resin.

27. (Withdrawn) The integral electronic device according to claim 26, wherein said light-emitting element is held within said opening via a photo-curing insulating resin.

28. (Withdrawn) The integral electronic device according to claim 25, wherein said light-emitting element is held within said opening via a photo-curing insulating resin.

29. (Withdrawn) The integral electronic device according to claim 24, wherein said first board comprises a board of any one of glass, ceramic and an organic resin.

30. (Withdrawn) The integral electronic device according to claim 29, wherein said electronic component is held within said opening via a photo-curing insulating resin.

31. (Withdrawn) The integral electronic device according to claim 24, wherein said electronic component is held within said opening via a photo-curing insulating resin.

32. (Withdrawn) The integral electronic device according to claim 24, wherein said second board is electrically connected to said electronic component via a flat metallic bump.

33. (Withdrawn) The integral electronic device according to claim 24, wherein said electronic component is held within said opening via an insulating resin that surrounds said electronic component except for upper and lower surfaces of said electronic component.

34. (Withdrawn) The integral electronic device according to claim 33, wherein said second board is electrically connected to said electronic component by being electrically connected to said upper surface of said electronic component, said integral electronic device further comprising:

a third board electrically connected to said lower surface of said electronic component.

35. (Withdrawn) The integral electronic device according to claim 24, further comprising:

another electronic component held within another opening that extends completely through the thickness of said first board,

wherein said second board is electrically connected to said another electronic component, with said opening and said another opening being parallel to one another.

36. (Currently amended) The method according to claim 11, wherein electrically connecting a second board to said ~~electronic component~~ plurality of LEDs comprises electrically connecting a said second board to said ~~electronic component~~ plurality of LEDs while said ~~electronic component~~ plurality of LEDs is held in said ~~opening~~ openings.

37. (New) The method according to claim 13, wherein holding said plurality of LEDs in said openings comprises holding said plurality of LEDs in said openings of a board of any one of glass, ceramic and an organic resin.